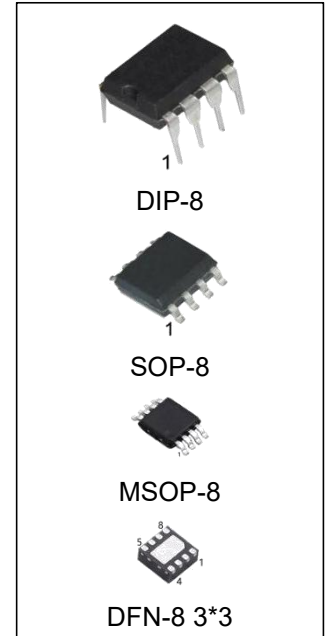


## DC-to- DC Converter Control Circuits

### FEATURES

- Operation from 3.0V to 40V input
- Low standby current
- Current limiting
- Output switch current up to 1.5A
- Adjustable output voltage
- Operation at frequencies up to 100kHz
- Precision reference (2%)



### ORDERING INFORMATION

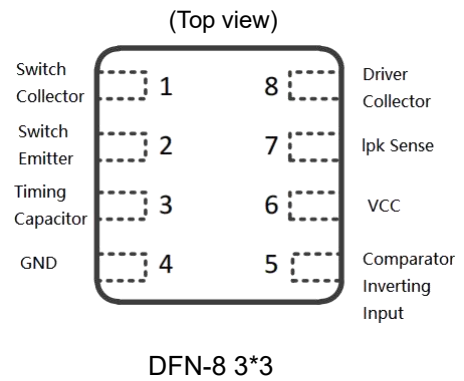
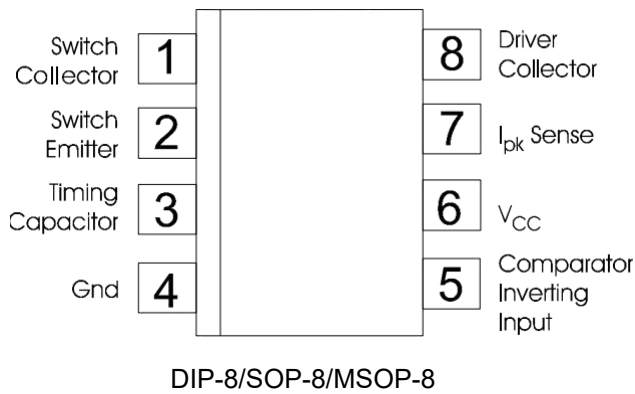
DEVICE	Package Type	MARKING	Packing	Packing Qty
MC34063N	DIP-8	MC34063,34063	TUBE	2000pcs/box
MC34063M/TR	SOP-8	MC34063,34063	REEL	2500pcs/reel
MC34063MM/TR	MSOP-8	34063	REEL	3000pcs/reel
MC34063DQ/TR MC34063DQ3/TR	DFN-8 3*3	34063	REEL	5000pcs/reel

### DESCRIPTION

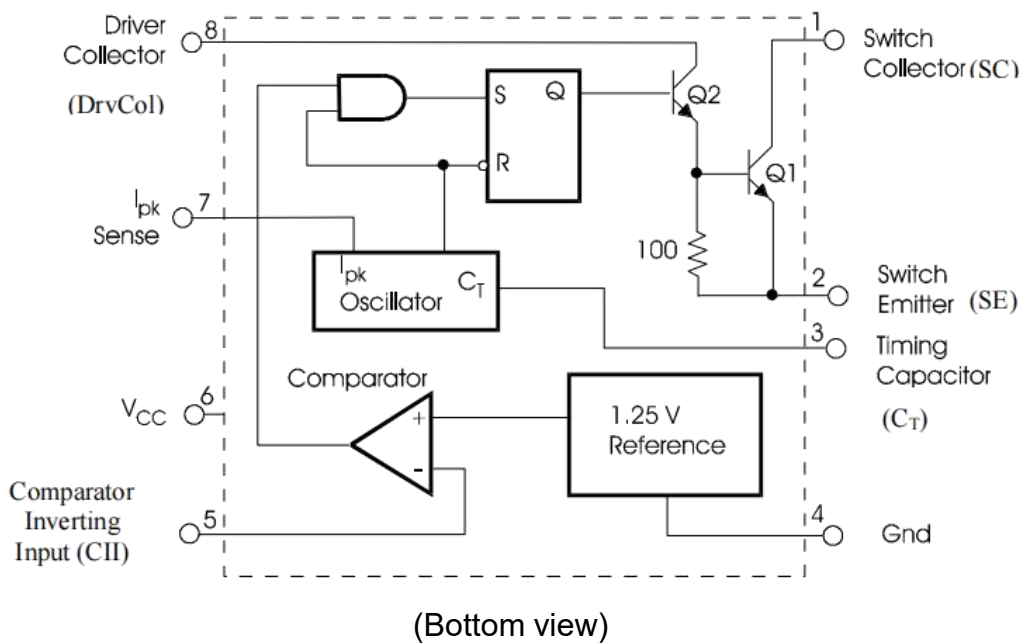
The MC34063 series is a monolithic control circuit containing primary functions required for DC-to-DC converters.

These devices consist of an internal temperature-compensated reference, comparator, controlled duty cycle oscillator with an active current limit circuit, driver and high current output switch. This series was specifically designed to be incorporated in step-down and step-up and voltage-inverting applications with a minimum number of external components.

**PIN CONNECTIONS**



**SCHEMATIC DIAGRAM**



## ABSOLUTE MAXIMUM RATINGS

Rating	Symbol	Value	Unit
Power supply voltage	$V_{CC}$	40	V
Comparator input voltage range	$V_{IR}$	-0.3 to +40	V
Switch collector voltage	$V_{C(Switch)}$	40	V
Switch emitter voltage (VPin1=40V)	$V_{E(Switch)}$	40	V
Switch collector-to-emitter voltage	$V_{CE(Switch)}$	40	V
Driver collector voltage	$V_{C(Driver)}$	40	V
Driver collector current (Note 1)	$I_{C(Driver)}$	100	mA
Switch current	$I_{Sw}$	1.5	A
Operating junction temperature	$T_J$	+150	°C
Operating ambient temperature range	$T_A$	-40 to +85	°C
Storage temperature range	$T_{STG}$	-65 to +150	°C
ESD (HBM)		2500	V
Lead Temperature (Soldering, 10 seconds)	$T_L$	260	°C

**Note:** Absolute Maximum Ratings indicate limits beyond which damage to the device may occur. Operating Ratings indicate conditions for which the device is intended to be functional, but specific performance is not ensured.

## ELECTRICAL CHARACTERISTICS ( $V_{CC}=5.0V$ , $T_A=T_{Low}$ to $T_{High}$ , unless otherwise specified.)

Characteristics	Symbol	Min	Typ	Max	Unit
<b>OSCILLATOR</b>					
Frequency (VPin5=0V, $C_T=1.0nF$ , $T_A=25^\circ C$ )	fosc	24	33	42	kHz
Charge current ( $V_{CC}=5.0V$ to 40V, $T_A=25^\circ C$ )	Ichg	24	35	42	$\mu A$
Discharge current ( $V_{CC}=5.0V$ to 40V, $T_A=25^\circ C$ )	Idischg	140	220	260	$\mu A$
Discharge-to-charge current ratio (Pin7 to $V_{CC}$ , $T_A=25^\circ C$ )	Idischg/Ichg	5.2	6.5	7.5	-
Current limit sense voltage (Ichg=Idischg, $T_A=25^\circ C$ )	Vlpk(sense)	250	300	350	mV
<b>OUTPUT SWITCH (Note 2)</b>					
Saturation voltage, Darlington connection ISw=1.0A, Pins1, 8 connected	$V_{CE(sat)}$	-	1.0	1.3	V
Saturation voltage, Darlington connection (ISw=1.0A, $R_{Pin8}=82\Omega$ to $V_{CC}$ , forced $\beta=20$ )	$V_{CE(sat)}$	-	0.45	0.7	V
DC current gain (ISw=1.0A, $V_{CE}=5.0$ , $T_A=25^\circ C$ )	$h_{FE}$	50	75	-	-
Collector off-state current ( $V_{CE}=40V$ )	$I_{C(off)}$	-	1.0	100	$\mu A$
<b>COMPARATOR</b>					
Threshold voltage	$V_{th}$	1.225 1.21	1.25 -	1.275 1.29	V
Threshold voltage line regulation ( $V_{CC}=3.0V$ to 40V)	Reg <sub>line</sub>	-	1.4	5.0	mV
Input bias current ( $V_{in}=0V$ )	$I_{IB}$	-	-20	-400	nA
<b>TOTAL DEVICE</b>					
Supply current ( $V_{CC}=5.0V$ to 40V, $C_T=1.0nF$ , Pin7= $V_{CC}$ , VPin5>>Vth, Pin2 =Gnd, remaining pins - open)	$I_{CC}$	-	-	4.0	mA

**Notes:** 1. Maximum package power dissipation limits must be observed.  
 2. Low duty cycle pulse techniques are used during the test to maintain the junction temperature as close to the ambient temperature as possible.

**TYPICAL PERFORMANCE CHARACTERISTICS**

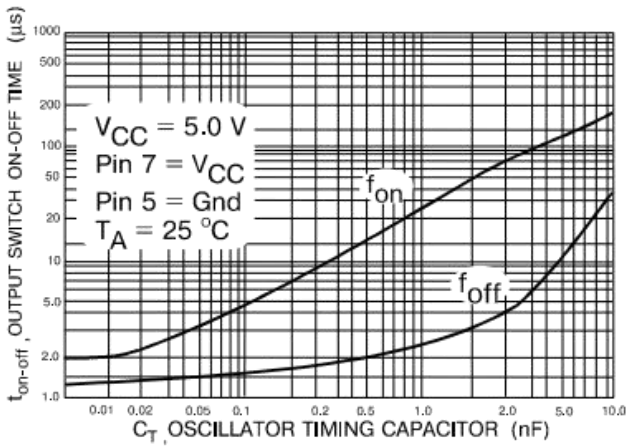


Fig.1. Output Switch on-off time versus Oscillator timing capacitor

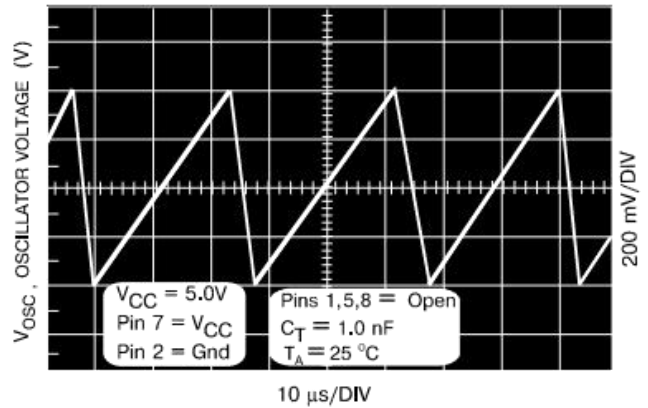


Fig.2. Timing capacitor waveform

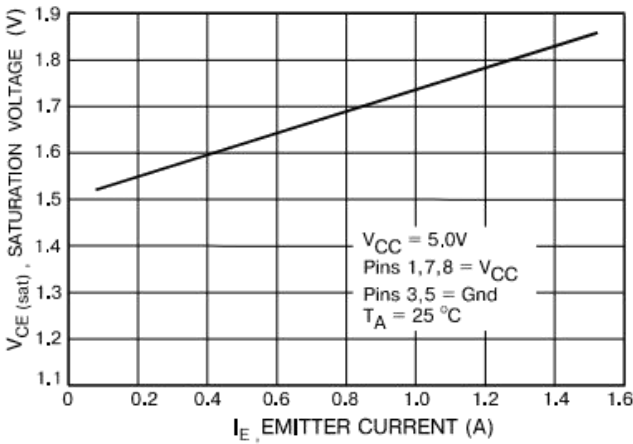


Fig.3. Emitter follower configuration output saturation voltage versus Emitter current

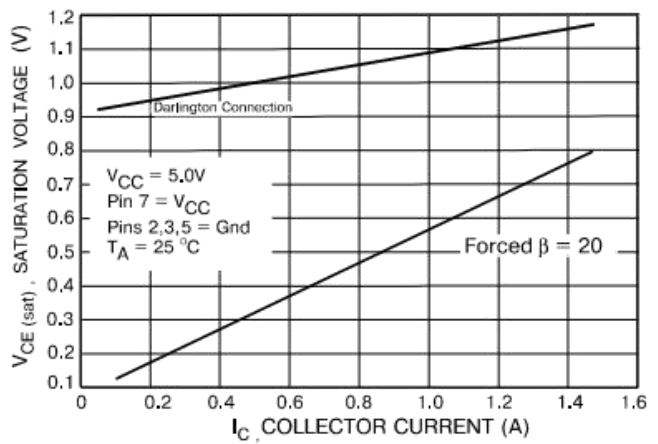


Fig.4. Common emitter configuration output saturation voltage versus Collector current

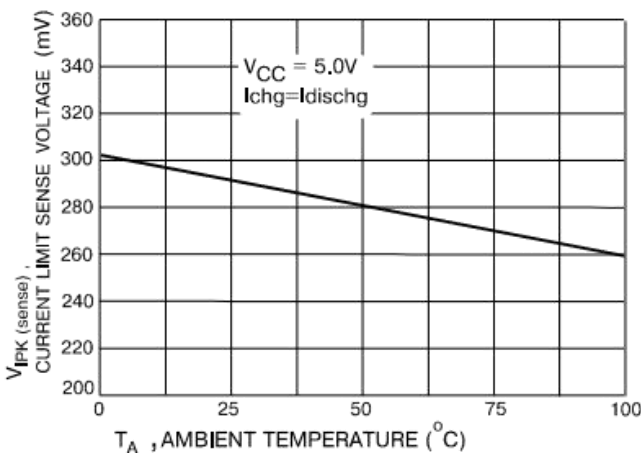


Fig.5. Current limit sense voltage versus Temperature

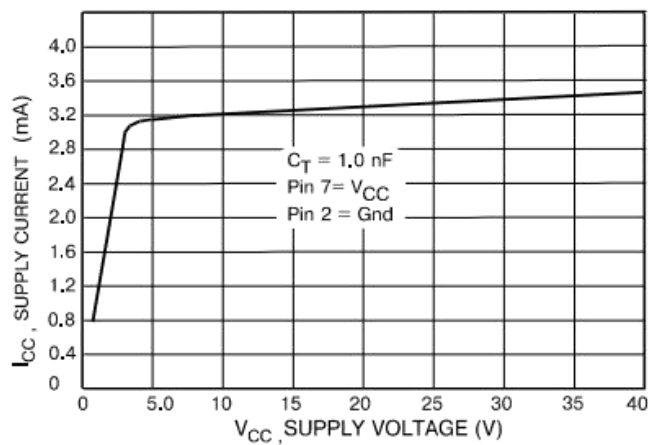
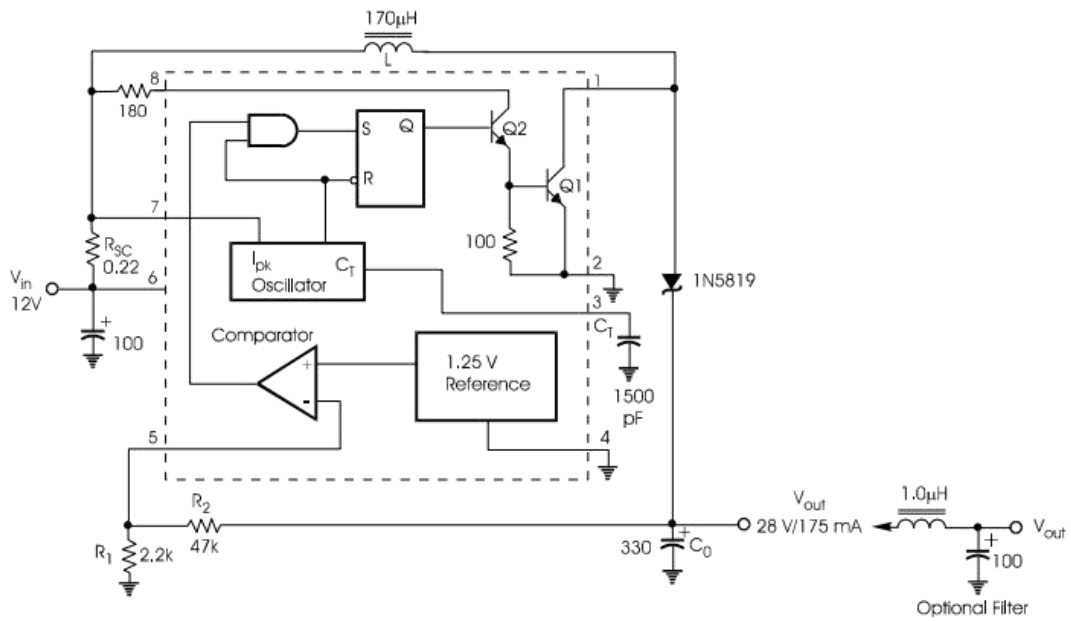


Fig.6. Standby supply current versus Supply voltage

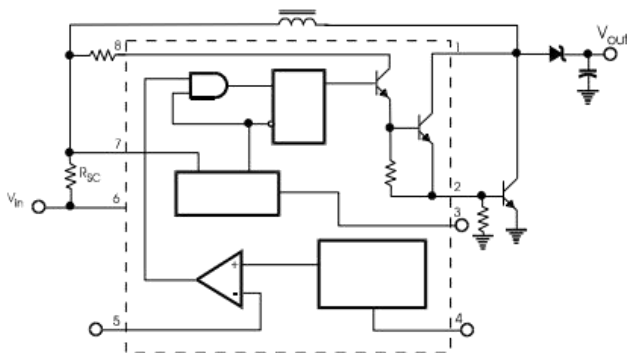
**APPLICATION INFORMATION**

**Fig.1. Step-up converter**

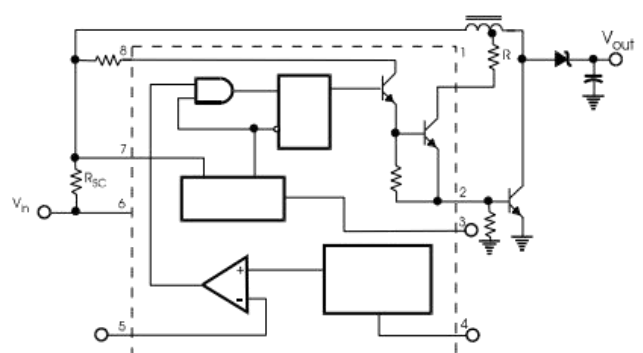


**Fig.2. External current boost connections for IC Peak greater than 1.5A**

**2a. External NPN switch**

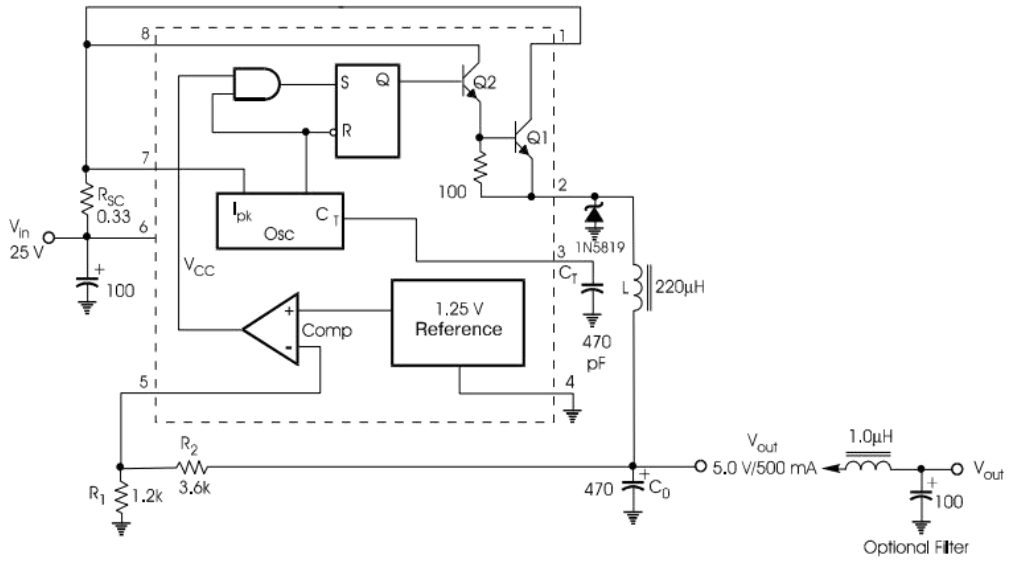


**2b. External NPN saturated switch**



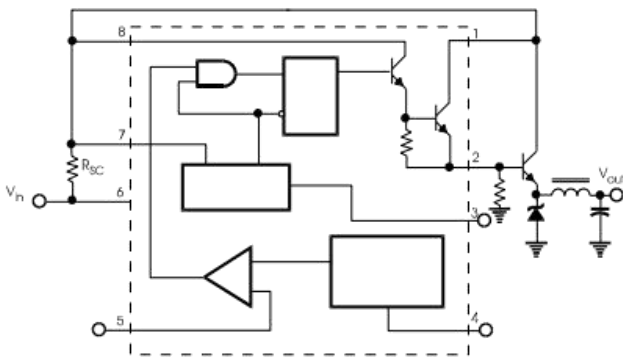
Note: R → 0 at constant VIN

**Fig.3. Step-down Converter**

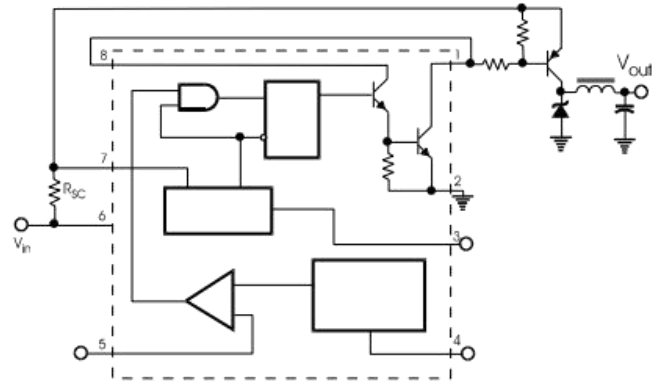


**Fig.4. External current boost connections for  $I_{C\ Peak}$  greater than 1.5A**

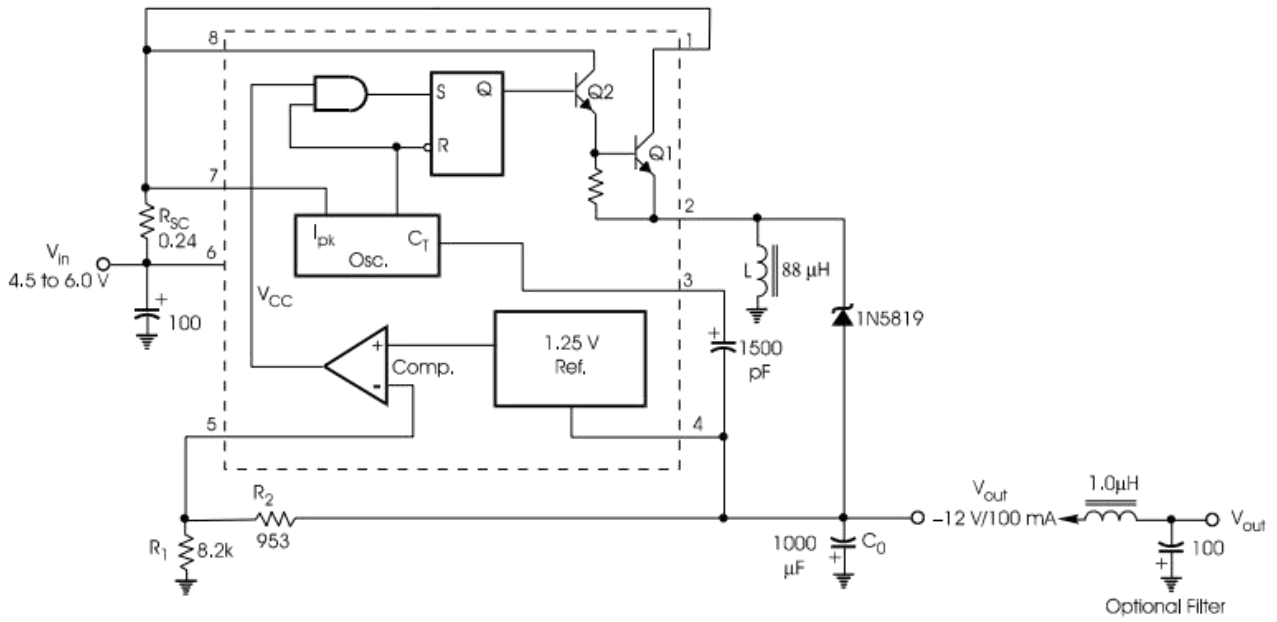
**4a. External NPN switch**



**4b. External PNP saturated switch**



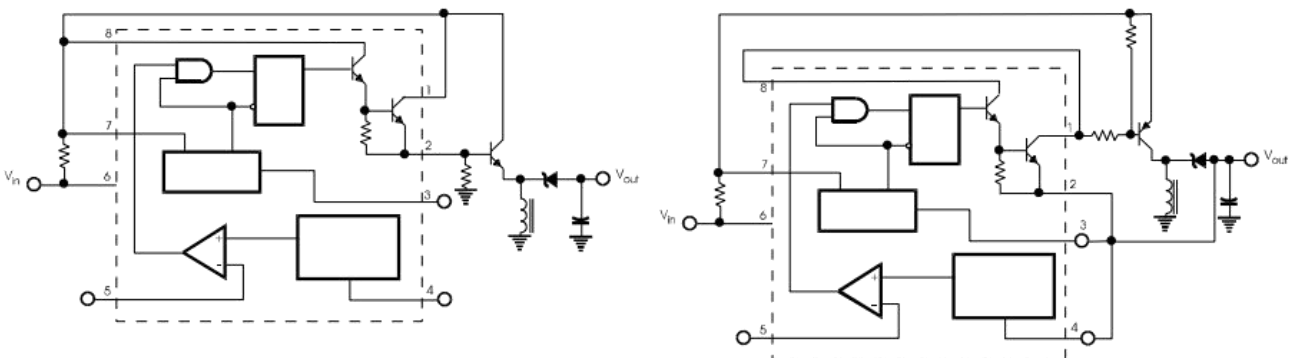
**Fig.5. Voltage inverting converter**



**Fig.6. External current boost connections for Ic Peak greater than 1.5A**

**6a. External NPN switch**

**6b. External PNP saturated switch**



**DESIGN FORMULA**

Calculation	Step-up	Step-down	Voltage-inverting
$t_{on}$	$\frac{V_{out} + V_F - V_{in(min)}}{V_{in(min)} - V_{sat}}$	$\frac{V_{out} + V_F}{V_{in(min)} - V_{sat} - V_{out}}$	$\frac{ V_{out}  + V_F}{V_{in} + V_{sat}}$
$(t_{on} + t_{off})_{max}$	$\frac{1}{f_{min}}$	$\frac{1}{f_{min}}$	$\frac{1}{f_{min}}$
$C_T$	$4.0 \times 10^{-5} t_{on}$	$4.0 \times 10^{-5} t_{on}$	$4.0 \times 10^{-5} t_{on}$
$I_{pk(switch)}$	$2I_{out(max)} \left( \frac{t_{on}}{t_{off}} + 1 \right)$	$2I_{out(max)}$	$2I_{out(max)} \left( \frac{t_{on}}{t_{off}} + 1 \right)$
$R_{sc}$	$0.3/I_{pk(Switch)}$	$0.3/I_{pk(Switch)}$	$0.3/I_{pk(Switch)}$
$L(min)$	$\left( \frac{V_{in(min)} - V_{sat}}{I_{pk(switch)}} \right) \times t_{on(max)}$	$\left( \frac{V_{in(min)} - V_{sat} - V_{out}}{I_{pk(switch)}} \right) \times t_{on(max)}$	$\left( \frac{V_{in(min)} - V_{sat}}{I_{pk(switch)}} \right) \times t_{on(max)}$
$C_o$	$9 \frac{I_{out} t_{on}}{V_{ripple(pp)}}$	$\frac{I_{pk(switch)}(t_{on} + t_{off})}{8V_{ripple(pp)}}$	$9 \frac{I_{out} t_{on}}{V_{ripple(pp)}}$

**TERMS AND DEFINITIONS**

$V_{sat}$  – Saturation voltage of the output switch.

$V_F$  – Forward voltage drop of the output rectifier.

**The following power supply characteristics must be chosen:**

$V_{in}$  – Nominal input voltage.

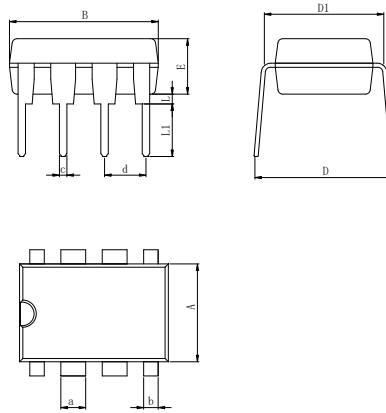
$V_{out}$  – Desired output voltage,  $|V_{out}| = 1.25 \left( 1 + \frac{R_2}{R_1} \right)$

$f_{min}$  – Minimum desired output switching frequency at the selected values of  $V_{in}$  and  $I_{out}$ .

$V_{ripple(p-p)}$  – Desired peak-to-peak output ripple voltage. In practice, the calculated capacitor value will need to be increased due to its equivalent series resistance and board layout. The ripple voltage should be kept to a low value since it will directly affect the line and load regulation.

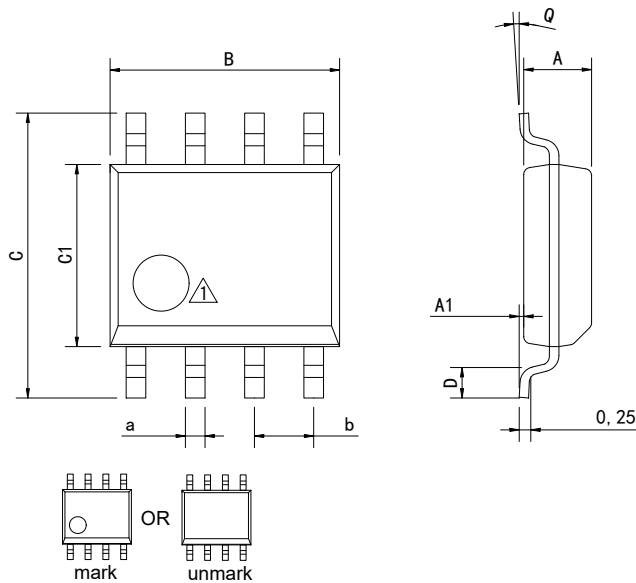
## Physical Dimensions


### DIP-8



Dimensions In Millimeters(DIP-8)											
Symbol:	A	B	D	D1	E	L	L1	a	b	c	d
Min:	6.10	9.00	8.10	7.42	3.10	0.50	3.00	1.50	0.85	0.40	2.54 BSC
Max:	6.68	9.50	10.9	7.82	3.55	0.70	3.60	1.55	0.90	0.50	

### SOP-8

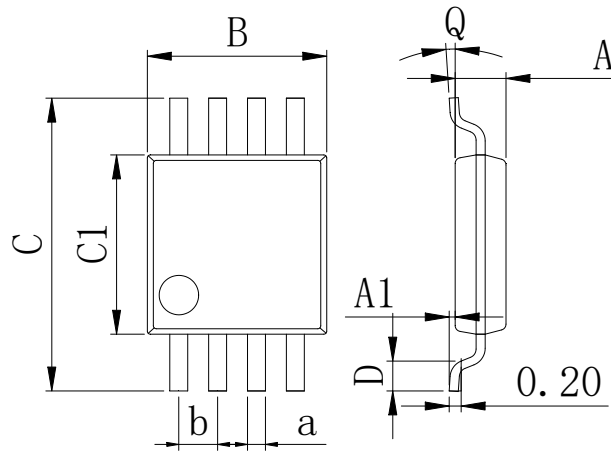


 Package top mark may be in lower left corner or unmark

Dimensions In Millimeters(SOP-8)									
Symbol:	A	A1	B	C	C1	D	Q	a	b
Min:	1.35	0.05	4.90	5.80	3.80	0.40	0°	0.35	1.27 BSC
Max:	1.55	0.20	5.10	6.20	4.00	0.80	8°	0.45	

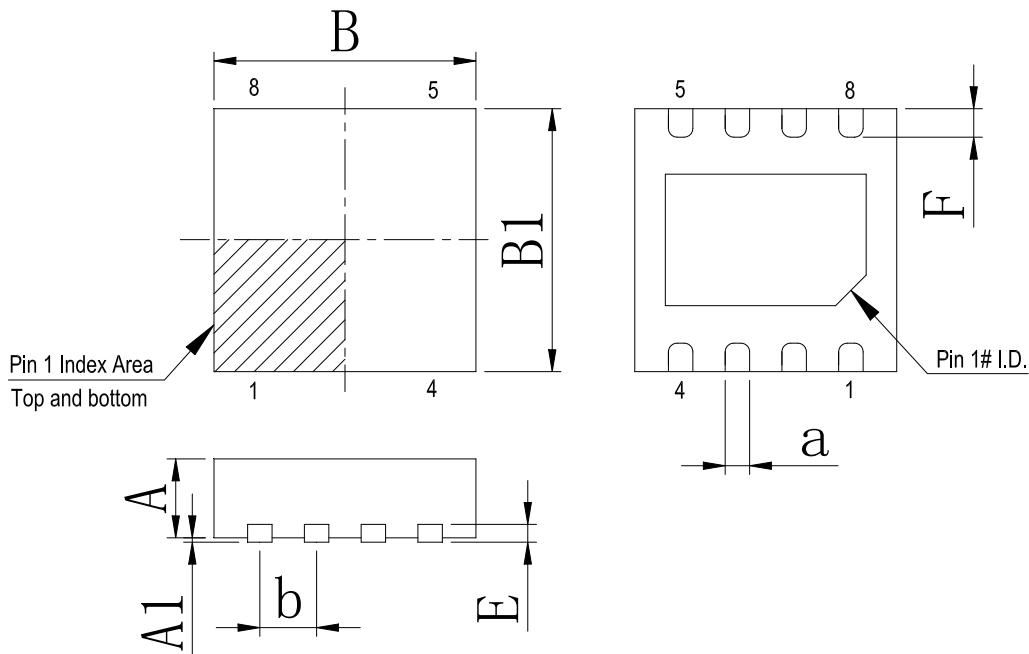
## Physical Dimensions

MSOP-8



Dimensions In Millimeters(MSOP-8)									
Symbol:	A	A1	B	C	C1	D	Q	a	b
Min:	0.80	0.05	2.90	4.75	2.90	0.35	0°	0.25	0.65 BSC
Max:	0.90	0.20	3.10	5.05	3.10	0.75	8°	0.35	

DFN-8 3\*3



Dimensions In Millimeters(DFN-8 3*3)								
Symbol:	A	A1	B	B1	E	F	a	b
Min:	0.85	0.00	2.90	2.90	0.20	0.30	0.20	0.65 BSC
Max:	0.95	0.05	3.10	3.10	0.25	0.50	0.34	

## Revision History

REVISION NUMBER	DATE	REVISION	PAGE
V1.0	2014-6	New	1-12
V1.1	2017-9	Update encapsulation type	1
V1.2	2024-11	Add a model marking name、 Update Lead Temperature	1、 3
V1.3	2025-12	Update important statements、 Update SOP-8 Dimension drawing	9、 12

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